AMENDMENT AND RESPONSE UNDER 37 CFR § 1.116 - EXPEDITED PROCEDURE

Serial Number: 09/652,713

Filing Date: August 31, 2000

CHEMICAL DISPENSING SYSTEM FOR SEMICONDUCTOR WAFER PROCESSING

Page 2 Dkt: 303.928US5

IN THE CLAIMS

Please amend the claims as follows.

1.-35. (Canceled)

36. (Previously Presented) A device comprising:

a dispenser configured to release a chemical toward an edge bead of a substrate; and a splash controller concentrically positioned at least partially around said dispenser and physically unattached from the edge bead, the splash controller being configured to draw the chemical from at least one surface of the substrate and toward said splash controller, wherein said splash controller is configured to generate a gas pressure around the edge bead that is lower than an ambient gas pressure, and wherein said splash controller is configured to physically intercept the chemical.

- 37. (Previously Presented) The device in claim 36, wherein the splash controller is around the edge bead.
- 38. (Previously Presented) The device of claim 36, wherein the splash controller completely surrounds said dispenser.
- 39. (Previously Presented) The device of claim 36, wherein the dispenser has a diameter smaller than a diameter of the splash controller.
- 40. (Previously Presented) The device of claim 36, wherein said dispenser is configured to release a chemical on a first side of a wafer and a second side of the wafer toward an edge bead, wherein the splash controller completely surrounds said dispenser.

DO NOT enter Am 4/3/07